


Full Material Declaration for attached parts list

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	<p>Diotec Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, B.-W., 79423, Germany Declarations authorised by: Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 23 January 2013 [Approved on 28 November 2017, 08:00 GMT]

Materials and substances

Use/Location	Material group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	3.10000%	Gold	7440-57-5	11.50000%
			Silica, amorphous-fused	60676-86-0	26.00000%
			Silicon	7440-21-3	62.50000%
Die attach	Sn-Pb solder	0.70000%	Silver	7440-22-4	2.50000%
			Tin	7440-31-5	5.00000%
			Lead	7439-92-1	92.50000%
Encapsulation	EP (Epoxy resin)	63.60000%	Carbon black	1333-86-4	0.30000%
			Epoxy resin 89	26335-32-0	28.30000%
			Quartz sand	60676-86-0	71.40000%
Leadfinish	Tin plating	7.20000%	Silver	7440-22-4	3.50000%
			Tin	7440-31-5	96.50000%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	25.40000%	Copper	7440-50-8	100.00000%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
ABS	Bridge Rectifier Dual Inline	0.1	g